

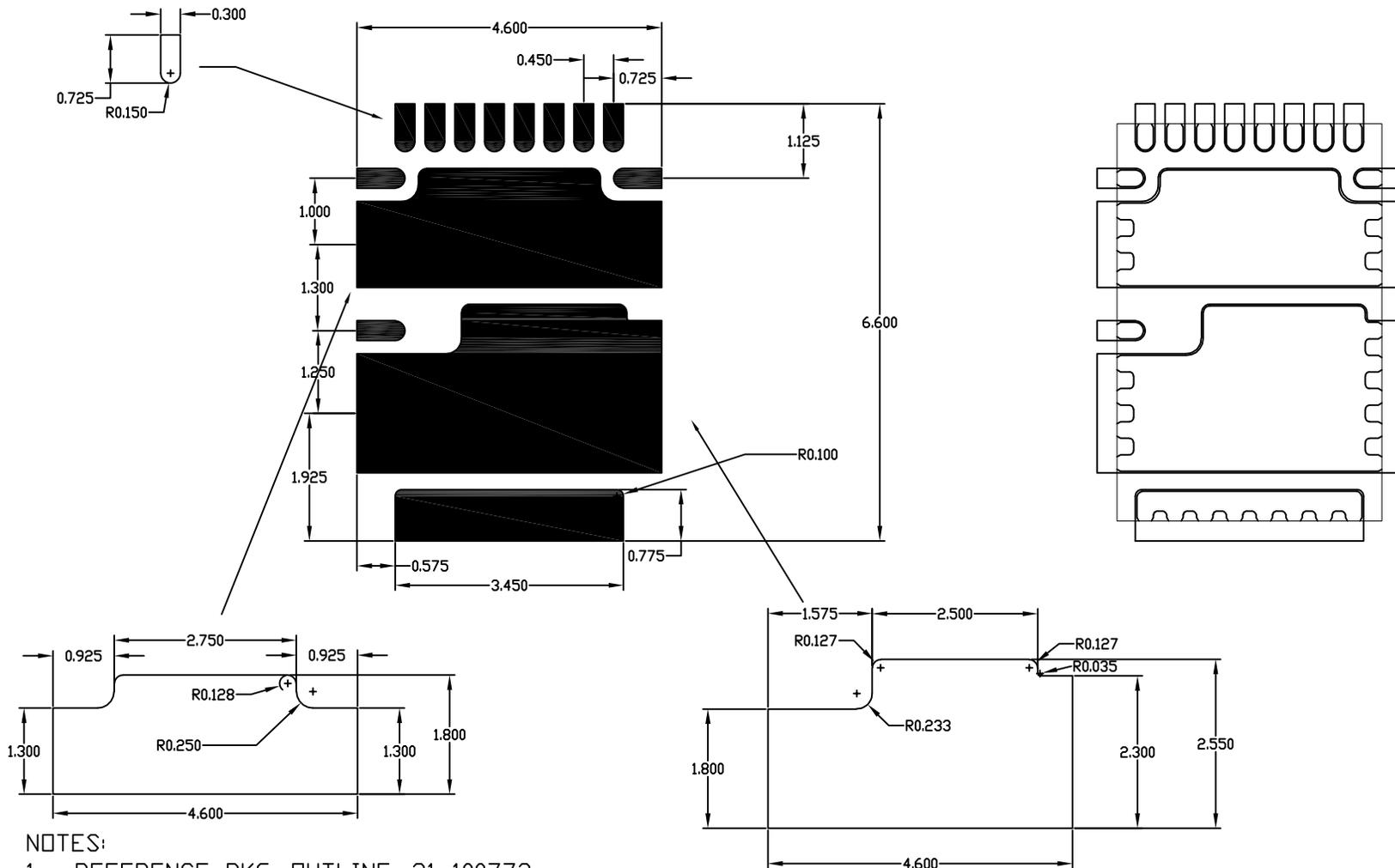


DOCUMENT TYPE: PLP
DOCUMENT ID #: 90-100277
REVISION: A-000
DOCUMENT TITLE: PACKAGE LAND PATTERN, [V3446FN+1F] FC2QF
EFFECTIVE DATE: 10/18/2024
EXPIRATION DATE:
CHANGE NUMBER: 1218995
ORIGINATOR: Aurelio Giron Jr.

REASON FOR CHANGE:
INITIAL RELEASE

RECOMMENDED LAND PATTERN

PACKAGE OVERLAY



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100773
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, P₆FREE PACKAGES.
5. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Analog Devices Inc. (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <https://www.analog.com/en/support> for further questions.

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